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# IRFP460C

#### 500V N-Channel MOSFET

### **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies and power factor corrections.

### **Features**

- 20A, 500V,  $R_{DS(on)} = 0.24\Omega @V_{GS} = 10 V$
- Low gate charge (typical 130nC)
- Low Crss (typical 60 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	IRFP460C	Units
V <sub>DSS</sub>	Drain-Source Voltage	500	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)	20	Α
	- Continuous (T <sub>C</sub> = 100°C)	12.5	Α
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	80	Α
V <sub>GSS</sub>	Gate-Source Voltage	± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	1050	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)	20	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	23.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)		W
	- Derate above 25°C	1.88	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C
TL	Maximum lead temperature for soldering purposes,		°C
.r	1/8" from case for 5 seconds	300	O

### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.53	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Ch	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	500			V
ΔBV <sub>DSS</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.55		V/°C
DSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V			10	μΑ
	Zero Gate voltage Drain Current	$V_{DS} = 400 \text{ V}, T_{C} = 125^{\circ}\text{C}$			100	μΑ
GSSF	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
GSSR	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Ch	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0	4	4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10.0 A		0.2	0.24	Ω
9FS	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 10.0 A (Note 4)	/	18		S
Dynan	nic Characteristics					
C <sub>iss</sub>	Input Capacitance			4590	6000	pF
Coss	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		380	460	pF
2 <sub>rss</sub>	Reverse Transfer Capacitance	f = 1.0 MHz		60	80	pF
d(on)	Turn-On Delay Time	V - 250 V I - 20 A	/	50	120	ns
r r	Turn-On Rise Time	V <sub>DD</sub> = 250 V, I <sub>D</sub> = 20 A,		150	310	ns
d(off)	Turn-Off Delay Time	$R_G = 25 \Omega$	7	380	770	ns
f	Turn-Off Fall Time	(Note 4, 5)		180	370	ns
Q <sub>g</sub>	Total Gate Charge			130	170	nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS} = 400 \text{ V}, I_{D} = 20 \text{ A},$		20		nC
$Q_{gd}$	Gate-Drain Charge	V <sub>GS</sub> = 10 V (Note 4, 5)		45		nC
Drain-S	ource Diode Characteristics ar					
S	Maximum Continuous Drain-Source Diode Forward Current 20  Maximum Pulsed Drain-Source Diode Forward Current 80				A	
SM /	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 20 A			80	A V
/ <sub>SD</sub>		$V_{GS} = 0 \text{ V, } I_S = 20 \text{ A}$ $V_{GS} = 0 \text{ V, } I_S = 20 \text{ A,}$	-	400	1.4	
rr Qrr	Reverse Recovery Time Reverse Recovery Charge	$dl_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)		480		ns
×rr	Reverse Recovery Charge	(Note 4)	K	7.7	-1-(	μC
L = 5.1mH, I $I_{SD} \le 20A$ , o Pulse Test :	ating : Pulse width limited by maximum junction temper $_{AS} = 20A$ , $V_{DD} = 50V$ , $R_G = 25~\Omega$ , Starting $T_J = 25^{\circ}C$ dividt $\leq 200A/\mu s$ , $V_{DD} \leq BV_{DSS}$ , Starting $T_J = 25^{\circ}C$ Pulse width $\leq 300\mu s$ , Duty cycle $\leq 2\%$ adependent of operating temperature	rature				
_coondany II	aspension of operating temperature					

# **Typical Characteristics**

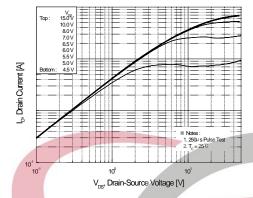


Figure 1. On-Region Characteristics

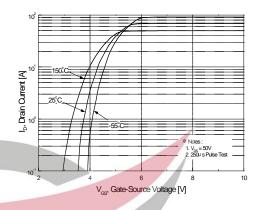


Figure 2. Transfer Characteristics

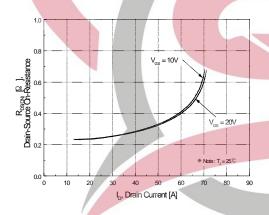


Figure 3. On-Resistance Variation vs
Drain Current and Gate Voltage

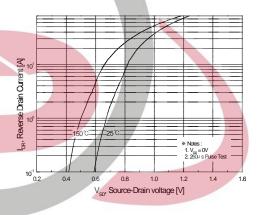


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

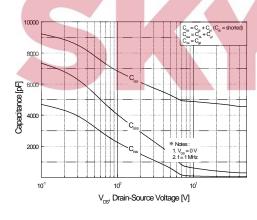


Figure 5. Capacitance Characteristics

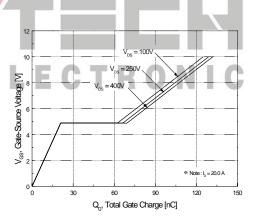
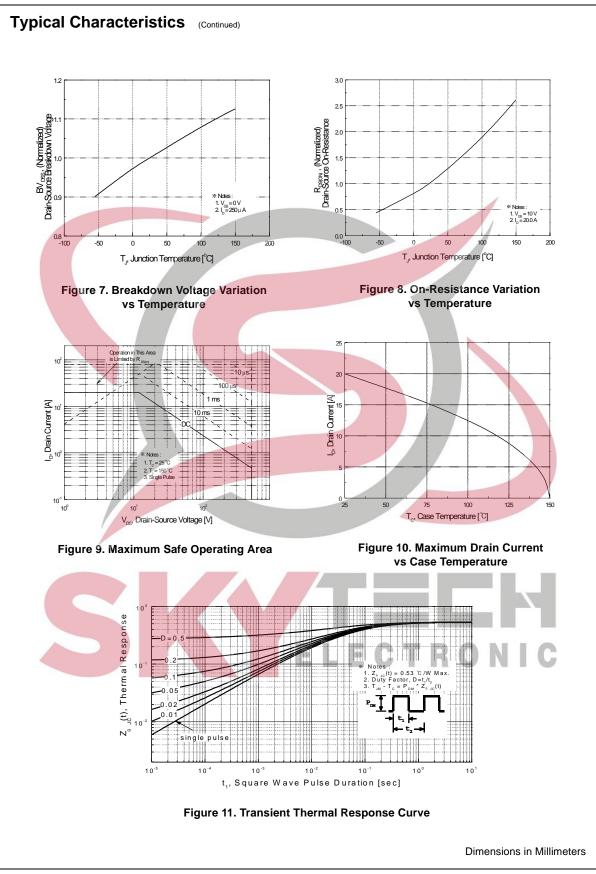
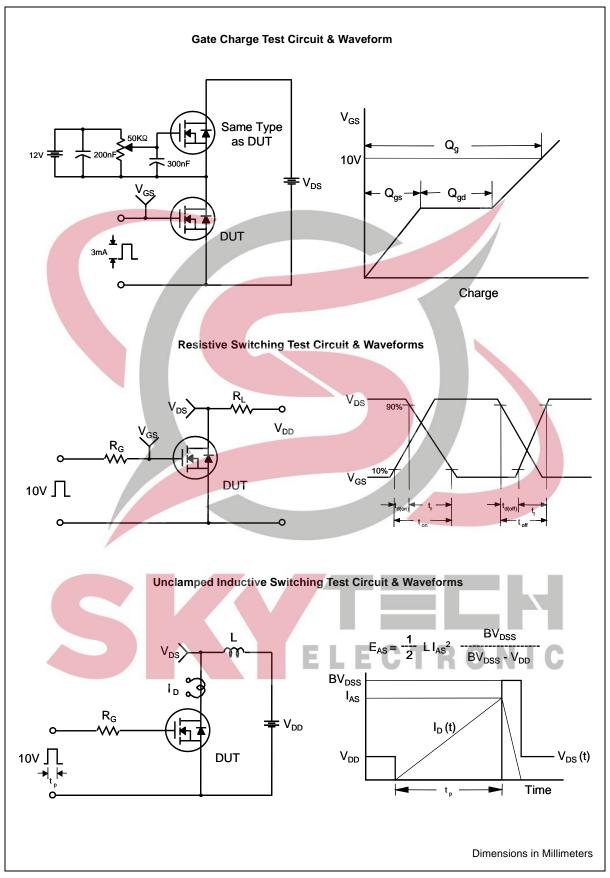


Figure 6. Gate Charge Characteristics

Dimensions in Millimeters

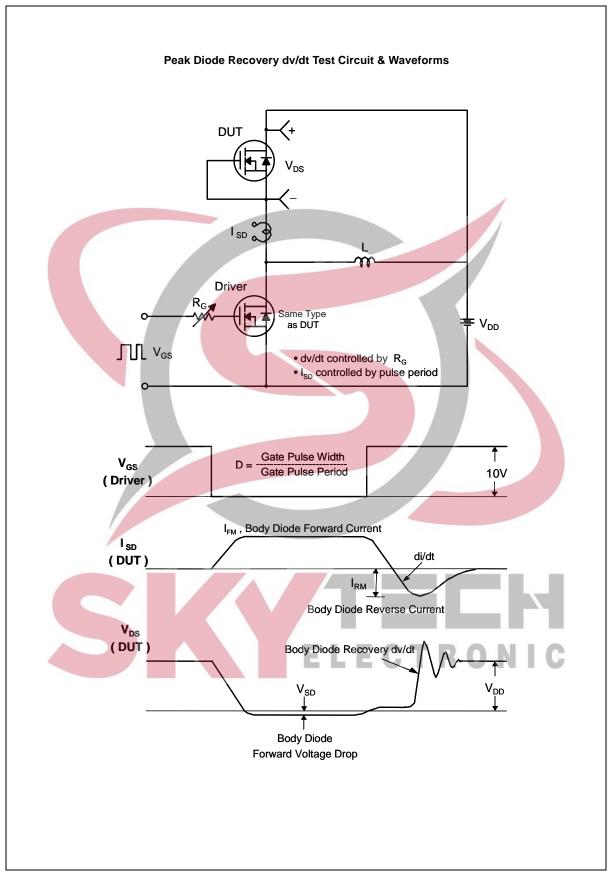


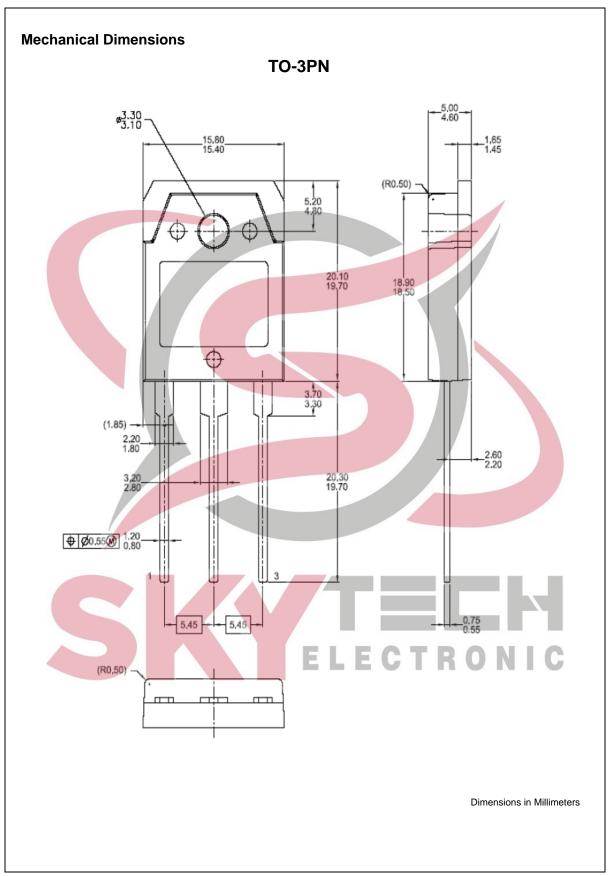




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DOME™	HiSeC™	PowerTrench <sup>®</sup>	SuperSOT™-8	
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